

Customer Owned Tooling is an advanced and flexible semicustom approach which allows highly experienced customers to translate their system know-how onto. SGS-THOMSON has the most advanced technologies in the marketplace.

INTERFACE

Phases	SGS-THOMSON	CUSTOMER
Specification	Provides Process Design Rules, Electrical Parameters and Testing Guidelines, Standard protected I/O Library	Provides Design Database, Bonding Diagram and Test Program
Prototype	Accepts Design database after DRC verification Incorporates scribe line alignment markers Release design to reticle generation Processes wafer lot to customer specification	Accepts prototype wafer
Engineering	Provides documentation on process parameters and test results	
Production	Initially has a pricing policy based on die size	Requested to give advanced visibility of 3 to 6 months for variations in production supply

PROCESS TECHNOLOGY

Process Technology	Description
HF2CMOS 2.0 micron BiCMOS	Double Level Metal - Isolated vertical PNP
HF3CMOS 1.2 micron BiCMOS	Double Level Metal - Isolated vertical PNP
BiCMOS 4/4C 0.7 micron BiCMOS	Triple Level Metal - Isolated vertical PNP
HCMOS5LA 0.5 micron Analog CMOS	Triple Level Metal
BiCMOS5 0.5 micron BiCMOS	Triple Level Metal - Isolated vertical PNP